DATE: 16 December, 2021

PCN #: 2560

PCN Title: Additional Wafer Source (GFAB) and Additional Assembly and Test Site (SAT)

Dear Customer:

This is an announcement of change(s) to products that are currently being offered by Diodes Incorporated.

We request that you acknowledge receipt of this notification within 30 days of the date of this PCN. If you require samples for evaluation purposes, please make a request immediately. Please refer to the implementation date of this change as it is stated in the attached PCN form. Please contact your local Diodes sales representative to acknowledge receipt of this PCN and for any sample requests.

The changes announced in this PCN will not be implemented earlier than 90 days from the notification date stated in the attached PCN form.

Previously agreed upon customer specific change process requirements or device specific requirements will be addressed separately.

For questions or clarification regarding this PCN, please contact your local Diodes sales representative.

Sincerely,

Diodes Incorporated PCN Team

PRODUCT CHANGE NOTICE PCN-2560 REV 1

Notification Date:	Implementation Date:	Product Family:	Change Type:	PCN #:
16 December, 2021	16 March, 2022	Discrete	Wafer FAB Source and Assembly & Test Site	**2560**

TITLE
Additional Wafer Source (GFAB) and Additional Assembly and Test Site (SAT)
DESCRIPTION OF CHANGE
This PCN is being issued to notify customers that in order to assure continuity of supply, Diodes Incorporated has qualified an additional internal wafer source located in Greenock, Scotland (GFAB) and an additional internal assembly and test site (SAT) in Shanghai, China for select products listed below. Full electrical characterization and high reliability testing has been completed on representative part numbers to ensure no change to device functionality or electrical specifications in the datasheet. Refer to the attached qualification report embedded in this file (to view, download this PCN file then open it with a PDF viewer to see the attached qual report). There will be no change to the Form, Fit, or Function of affected products.
IMPACT
No change in datasheet parameters and product performance
PRODUCTS AFFECTED
Table 1: Additional wafer source (GFAB) Table 2: Additional wafer source (GFAB) and assembly and test site (SAT) Table 3: Additional wafer source (GFAB) and assembly mold compound change

WEB LINKS	
Manufacturer's Notice:	https://www.diodes.com/quality/product-change-notices/diodes-product-change-notices/
For More Information Contact:	https://www.diodes.com/about/contact-us/contact-sales/
Data Sheet:	https://www.diodes.com/catalog/

DISCLAIMER
Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.

Table 1 - Additional Wafer Source (GFAB)					
SDM01U50CP3-7	SDM05U20CSP-7	SDM1A40CSP-7	SDM1U30CP3-7	SDM2U20CSP-7	SDM2U40CSP-7B
SDM02L30CP3-7	SDM05U20S3-7	SDM1L20DCP3-7	SDM1U40CSP-7	SDM2U20SD3-7	SDM4A30EP3-7B
SDM02M30DCP3-7	SDM05U40CSP-7	SDM1L30CSP-7	SDM2A20CSP-7	SDM2U30CSP-7	SDM4A40EP3-7B
SDM02U30CSP-7	SDM1A30CSP-7	SDM1U20CSP-7	SDM2A40CSP-7B	SDM2U30CSP-7B	SDM5U45EP3-7
SDM05A30CP3-7	SDM1A40CP3-7				

Table 2 - Additional Wafer Source (GFAB) and Assembly and Test Site (SAT)					
SDT20100CTB-13	SDT60100CTB-13				

Table 3 - Additional Wafer Source (GFAB) and Assembly Mold Compound Change					
SDT5A100SAF-13	SDT5A100SB-13	SDT5H100SB-13			